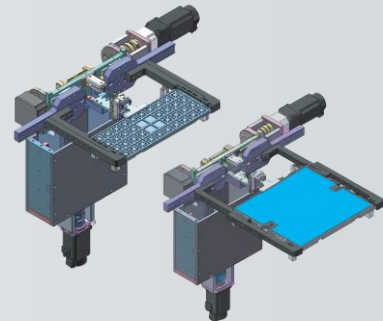


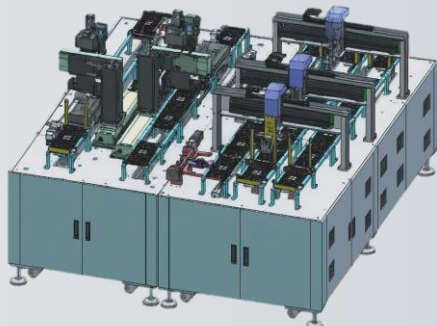
Aurca series



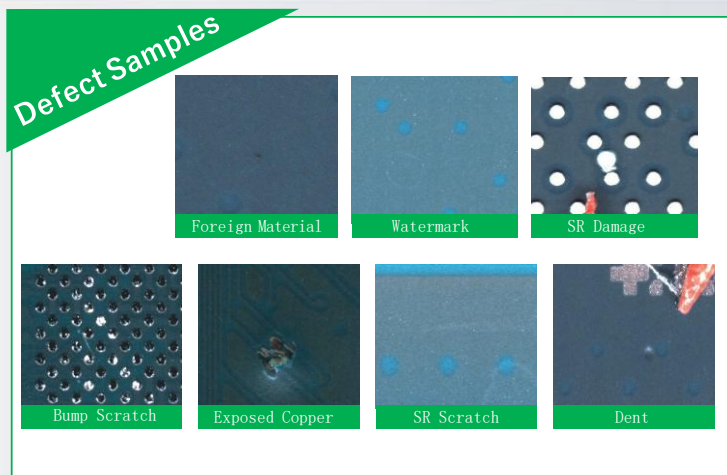
※插图仅供参考，如有变更恕不另行通知。
The illustration is for reference and subject to change without notice



可变导轨：可兼容JEDEC小型托盘和JEDEC大型托盘



Nidec Super Vision (S-Vision) Imaging System



■ 单次扫描即可生成多幅具有不同光学效果的全彩图像
Single scan generates multiple full-color images with different optical effects

■ 成像效率提升2~3倍*
Imaging efficiency increased 2-3*

■ 采用多通道独立光学系统
Multi-channel, independent optical paths

*一次扫描可同时获取3个通道的图像
Enabled by generating 3 optical channels in a single scan.

■ 先进的AI+CV算法与丰富的缺陷库相结合，可实现精确的缺陷分类与分析。

Advanced AI + CV algorithms and a rich defect library enable precise defect classification and analysis.

■ 自主研发的全光谱多维度照明系统，专为高精度检测定制。

A self-developed full-spectrum, multi-dimensional lighting system customized for high-precision inspection.

■ 兼容JEDEC小型和大型托盘，顺应行业向大尺寸格式及高效自动化处理的发展趋势。

Compatible with both JEDEC Small and Large Trays, aligning with the industry's shift toward larger formats and high-efficiency automated handling.

■ 实时良率监测支持生产决策，实现智能化质量管控与良率提升。

Real-time yield monitoring supports production decisions, enabling intelligent quality control and yield improvement.

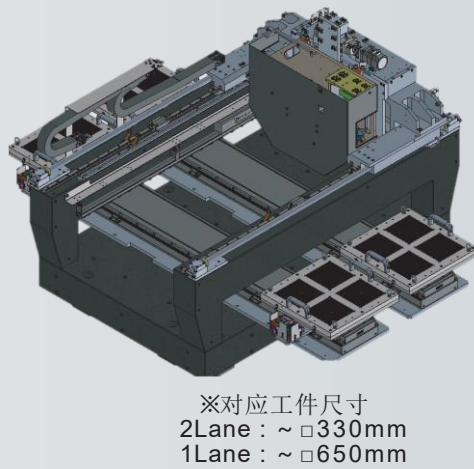
AFVI+AI Specifications

机器尺寸 Machine Size	可变导轨：4500 × 3800 × 1860mm (L×W×H) ※三色灯除外 Variable rail: 4500 × 3800 × 1860mm (L×W×H) ※Tri-color tower light not included.
可对应产品尺寸 Product Size	JEDEC Small Tray: 322.6×135.9mm JEDEC Large Tray: 537.6×258mm
光学参数 Visual Parameter	CCD: 3.5μm/2.5μm resolution; 16K color high-speed line scan; Robust Light Source
可检测缺陷 Defect Type	变色、裂纹、露铜、划痕、异物、凹痕、缺口、蚀刻不良、污染等 Discoloration, cracks, exposed copper, scratches, foreign matter, dents, notches etching defects, contamination, etc
循环时间 Cycle Time	JEDEC Small Tray: ≥60 tray/hr (分解能3.5μm) JEDEC Large Tray: ≥45 tray/hr (分解能3.5μm)

RSH series



※插图仅供参考，如有变更恕不另行通知。
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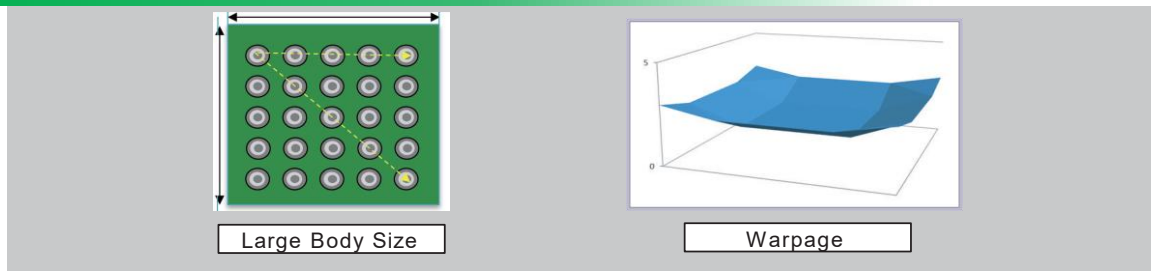
※对应工件尺寸
2Lane: ~ □330mm
1Lane: ~ □650mm

■ 在保持高精度、高分辨率的同时优化成本
实现高分辨率检测与高精度测量性能的完美结合
High Precision & Resolution

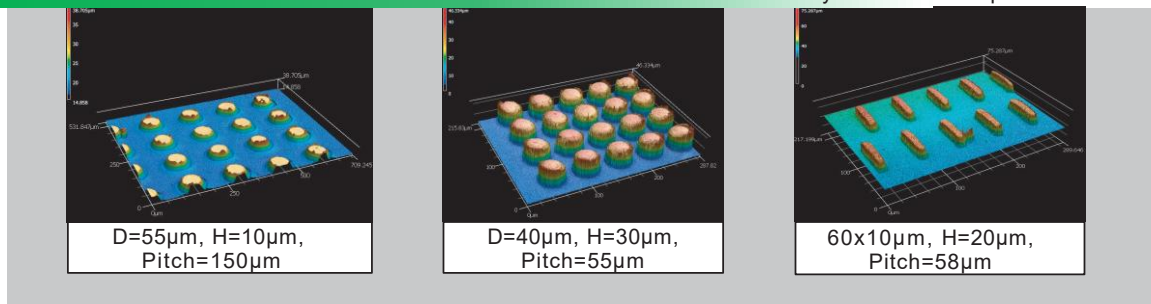
■ 全面支持大型基板与高密度凸块
可灵活应对更大尺寸基板、大量凸块、微小直径凸块及窄间距需求，同时兼容各类凸块形状与方向
Fully Compatible with Large Substrates & High-Density Bumps

■ 搭载最先进的软件与算法
配备强大分析功能 支持多核及先进封装的TTV/STV测量
Equipped with Cutting-Edge Software and Algorithms.

2D/3D Bump Metrology



Fine Pitch Bump Measurement



Various Bump Shapes and Orientations



2D/3D Bump Inspection Specification

Product Size	JEDEC Small Tray / JEDEC Large Tray / Full Panel
FOV	9.6mm
Resolution	2D(X): 1.83μm, 2D(Y): 1.83μm; 3D(X): 5μm, 3D(Y): Programmable, 3D(Z): 0.11μm
Min. Bump Size	20μm
Min. Bump Pitch	1.4x bump height
Applications	C4 area bump measurement Bump height, bump diameter, bump coplanarity, CAW, etc.

※以上基于RSH-8iF的规格。The above specifications are based on the RSH-8iF model.